

STGW30NC60VD

40 A, 600 V, very fast IGBT with Ultrafast diode

Features

- High current capability
- High frequency operation up to 50 KHz
- Very soft ultra fast recovery antiparallel diode

Applications

- High frequency inverters, UPS
- Motor drive
- SMPS and PFC in both hard switch and resonant topologies

Description

This device utilizes the advanced Power MESH™ process resulting in an excellent trade-off between switching performance and low on-state behavior.

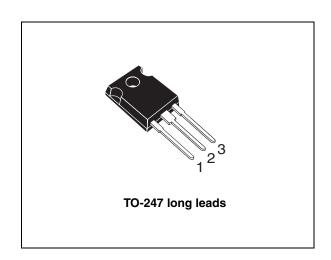


Figure 1. Internal schematic diagram

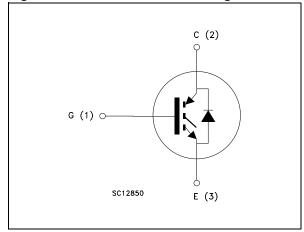


Table 1. Device summary

Order code	Order code Marking		Packaging	
STGW30NC60VD	GW30NC60VD	TO-247 long leads	Tube	

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STGW30NC60VD Electrical ratings

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V _{CES}	Collector-emitter voltage (V _{GE} = 0)	600	٧
I _C ⁽¹⁾	Continuous collector current at T _C = 25 °C	80	Α
I _C ⁽¹⁾	Continuous collector current at T _C = 100 °C	40	Α
I _{CP} ⁽²⁾	Pulsed collector current	150	Α
I _{CL} ⁽³⁾	Turn-off latching current	100	Α
V _{GE}	Gate-emitter voltage	± 20	٧
I _F	Diode RMS forward current at T _C = 25 °C	30	Α
I _{FSM}	Surge not repetitive forward current $t_P = 10$ ms sinusoidal	120	Α
P _{TOT}	Total dissipation at T _C = 25 °C	250	W
T _J	Operating junction temperature	FF to 150	°C
T _{STG}	Storage temperature	– 55 to 150	
TL	Maximum lead temperature for soldering purpose for 10 sec	300	°C

1. Calculated according to the iterative formula:

$$I_{C}(T_{C}) = \frac{T_{j(max)} - T_{C}}{R_{thj-c} \times V_{CE(sat)(max)}(T_{j(max)}, I_{C}(T_{C}))}$$

- 2. Pulse width limited by maximum junction temperature and turn-off within RBSOA
- 3. V_{clamp} = 80 % V_{CES} , T_J = 150 °C, R_G = 10 Ω , V_{GE} = 15 V

Table 3. Thermal data

Symbol	Parameter	Value	Unit
B	Thermal resistance junction-case IGBT	0.5	°C/W
R_{thJC}	Thermal resistance junction-case diode	1.5	°C/W
R _{thJA}	Thermal resistance junction-ambient	50	°C/W

Electrical characteristics STGW30NC60VD

2 Electrical characteristics

 $T_J = 25~^{\circ}C$ unless otherwise specified.

Table 4. Static

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)CES}	Collector-emitter breakdown voltage (V _{GE} = 0)	I _C = 1 mA	600			٧
V _{CE(sat)}	Collector-emitter saturation voltage	V _{GE} = 15 V, I _C =20 A V _{GE} = 15 V, I _C =40 A V _{GE} = 15 V, I _C =80 A,T _j =100 °C V _{GE} = 15 V, I _C =20 A,T _j =125 °C		1.8 2.1 2.9 1.7	2.5	>
V _{GE(th)}	Gate threshold voltage	$V_{CE} = V_{GE}, I_{C} = 250 \mu A$	3.75		5.75	٧
I _{CES}	Collector-cut-off current (V _{GE} = 0)	V _{CE} = 600 V V _{CE} = 600 V, T _j = 125 °C			10 1	μA mA
I _{GES}	Gate-emitter leakage current (V _{CE} = 0)	V _{GE} = ± 20V			±100	nA
9 _{fs}	Forward transconductance	V _{CE} = 15 V _, I _C = 20 A		15		S

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C _{ies} C _{oes} C _{res}	Input capacitance Output capacitance Reverse transfer capacitance	$V_{CE} = 25V, f = 1 \text{ MHz}, V_{GE} = 0$	-	2200 225 50	-	pF pF pF
Q _g Q _{ge} Q _{gc}	Total gate charge Gate-emitter charge Gate-collector charge	V_{CE} = 390V, I_{C} = 20A, V_{GE} = 15V, (see Figure 18)	-	100 16 45	140	nC nC nC

Table 6. Switching on/off (inductive load)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r (di/dt) _{onf}	Turn-on delay time Current rise time Turn-on current slope	V_{CC} =390 V, I_{C} = 20 A, R_{G} =3.3 Ω , V_{GE} =15V (see Figure 17)	1	31 11 1600	-	ns ns A/µs
t _{d(on)} t _r (di/dt) _{on}	Turn-on delay time Current rise time Turn-on current slope	V_{CC} =390 V, I_{C} = 20 A, R_{G} =3.3 Ω , V_{GE} =15 V T_{j} =125°C (see Figure 17)	1	31 11.5 1500	-	ns ns A/µs

Table 6. Switching on/off (inductive load)

t _{r(Voff)} t _{d(off)} t _f	Off voltage rise time Turn-off delay time Current fall time	V_{CC} =390 V, I_{C} = 20 A, R_{G} =3.3 Ω , V_{GE} =15 V (see Figure 17)	-	28 100 75	-	ns ns ns
t _{r(Voff)} t _{d(off)} t _f	Off voltage rise time Turn-off delay time Current fall time	V_{CC} =390 V, I_{C} = 20 A, R_{G} =3.3 Ω , V_{GE} =15 V T_{j} =125°C (see Figure 17)	-	66 150 130	-	ns ns ns

Table 7. Switching energy (inductive load)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
E _{on} ⁽¹⁾ E _{off} E _{ts}	Turn-on switching losses Turn-off switching losses Total switching losses	V_{CC} =390 V, I_{C} = 20 A, R_{G} =3.3 Ω , V_{GE} =15 V, (see Figure 19)	-	220 330 550	300 450 750	μJ μJ μJ
E _{on} ⁽¹⁾ E _{off} E _{ts}	Turn-on switching losses Turn-off switching losses Total switching losses	V_{CC} =390 V, I_{C} = 20 A, R_{G} =3.3 Ω , V_{GE} =15 V, T_{J} = 125°C (see Figure 19)	1	450 770 1220	-	րվ րվ րվ

Eon is the turn-on losses when a typical diode is used in the test circuit in *Figure 19*. Eon include diode recovery energy. If the IGBT is offered in a package with a co-pak diode, the co-pack diode is used as external diode. IGBTs & Diode are at the same temperature (25°C and 125°C)

Table 8. Collector-emitter diode

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _F	Forward on-voltage	I _F = 20 A I _F = 20 A, T _j = 125°C	-	1.8 1.4	2.3	V V
t _{rr} Q _{rr} I _{rrm}	Reverse recovery time Reverse recovery charge Reverse recovery current	I_F = 20 A, V_R = 40 V, T_j = 25°C, di/dt =100 A/ μ s (see Figure 20)	-	44 66 3	-	ns nC A
t _{rr} Q _{rr} I _{rrm}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_F = 2 \text{ 0A}, V_R = 40 \text{ V},$ $T_j = 125^{\circ}\text{C},$ $di/dt = 100 \text{ A/µs}$ (see Figure 20)	-	88 237 5.4	-	ns nC A

Electrical characteristics STGW30NC60VD

2.1 Electrical characteristics (curves)

Figure 2. Output characteristics

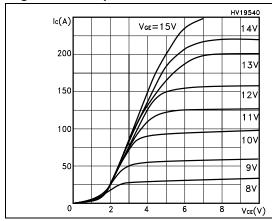


Figure 3. Transfer characteristics

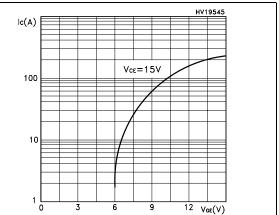
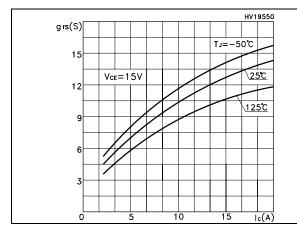


Figure 4. Trans conductance

Figure 5. Collector-emitter on voltage vs temperature



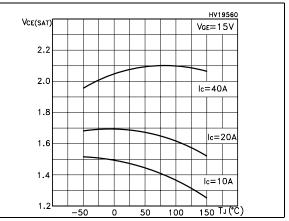
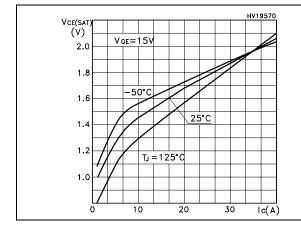


Figure 6. Collector-emitter on voltage vs collector current

Figure 7. Normalized gate threshold vs temperature



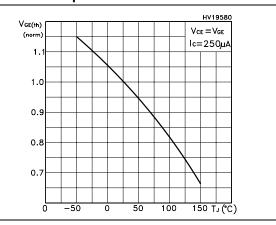
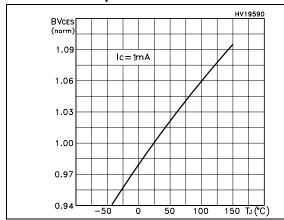


Figure 8. Normalized breakdown voltage vs Figure 9. Gate charge vs. gate-emitter voltage temperature



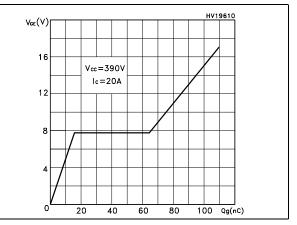
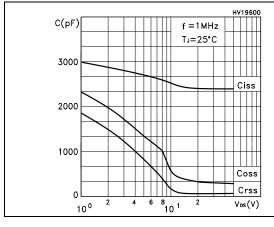


Figure 10. Capacitance variations

Figure 11. Switching losses vs temperature



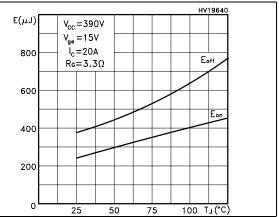
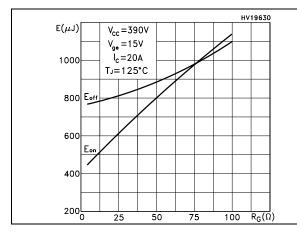
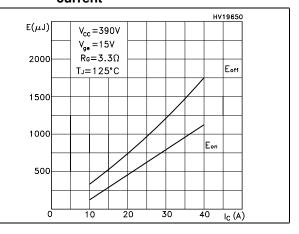


Figure 12. Switching losses vs. gate resistance Figure 13. Switching losses vs collector current

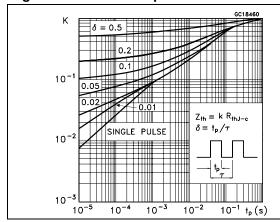




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Figure 14. Thermal impedance

Figure 15. Turn-off SOA



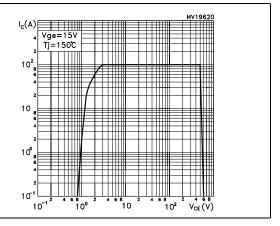
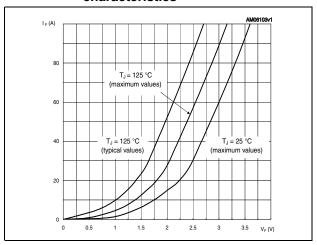


Figure 16. Emitter-collector diode characteristics

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STGW30NC60VD Test circuits

3 Test circuits

Figure 17. Test circuit for inductive load switching

Figure 18. Gate charge test circuit

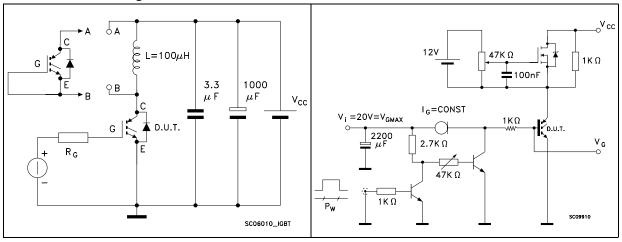
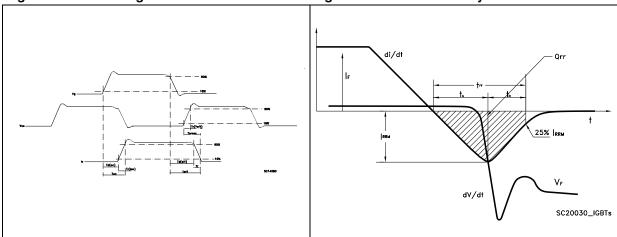


Figure 19. Switching waveforms

Figure 20. Diode recovery times waveform



4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Table 9. TO-247 long leads mechanical data

Dim	J	mm.	
Dim.	Min.	Тур.	Max.
А	4.90		5.15
D	1.85		2.10
E	0.55		0.67
F	1.07		1.32
F1	1.90		2.38
F2	2.87		3.38
G		10.90 BSC	
Н	15.77		16.02
L	20.82		21.07
L1	4.16		4.47
L2	5.49		5.74
L3	20.05		20.30
L4	3.68		3.93
L5	6.04		6.29
М	2.27		2.52
V		10°	
V1		3°	
V3		20°	
Dia.	3.55		3.66

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HEAT-SINK PLANE -D L₅ -D|A L3 F2 ·E BACK VIEW 7395426_E

Figure 21. TO-247 long leads drawing

Revision history STGW30NC60VD

5 Revision history

Table 10. Document revision history

Date	Revision	Changes
12-Feb-2007	1	First release.
19-Feb-2007	2	Figure 6 has been updated
12-Mar-2010	3	Inserted I _{FSM} parameter on <i>Table 2: Absolute maximum ratings</i> . Updated <i>Figure 16: Emitter-collector diode characteristics</i> and package mechanical data.
03-Jan-2011	4	Updated Table 4: Static, Table 8: Collector-emitter diode and Figure 14: Thermal impedance.
23-Feb-2011	5	Added T _L row <i>Table 2 on page 3</i> .

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